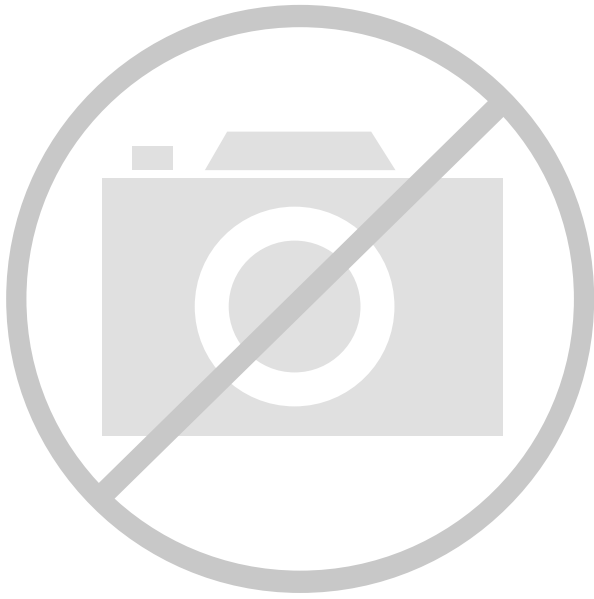




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	320
Number of Gates	-
Number of I/O	160
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5lv-320-160-20yi



Table 1. MACH 5 Device Features ¹

Feature	M5-128/1 M5LV-128		M5-192/1	M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
Supply Voltage (V)	5	3.3	5	5	3.3	5	3.3	5	3.3	5	3.3
Macrocells	128	128	192	256	256	320	320	384	384	512	512
Maximum User I/O Pins	120	120	120	160	160	192	160	160	160	256	256
t _{PD} (ns)	5.5	5.5	5.5	5.5	5.5	6.5	6.5	6.5	6.5	6.5	6.5
t _{SS} (ns)	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0
t _{COS} (ns)	4.5	4.5	4.5	4.5	4.5	5.0	5.0	5.0	5.0	5.0	5.0
f _{CNT} (MHz)	182	182	182	182	182	167	167	167	167	167	167
Typical Static Power (mA)	35	35	45	55	55	70	70	75	75	100	100
IEEE 1149.1 Boundary Scan Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI-Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Note:

1. "M5-xxx" is for 5-V devices. "M5LV-xxx" is for 3.3-V devices.

GENERAL DESCRIPTION

The MACH[®] 5 family consists of a broad range of high-density and high-I/O Complex Programmable Logic Devices (CPLDs). The fifth-generation MACH architecture yields fast speeds at high CPLD densities, low power, and supports additional features such as in-system programmability, Boundary Scan testability, and advanced clocking options (Table 1). The MACH 5 family offers 5-V (M5-xxx) and 3.3-V (M5LV-xxx) operation.

Manufactured in state-of-the-art ISO 9000 qualified fabrication facilities on E²CMOS process technologies, MACH 5 devices are available with pin-to-pin delays as fast as 5.5 ns (Table 2). The 5.5, 6.5, 7.5, 10, and 12-ns devices are compliant with the *PCI Local Bus Specification*.

Select devices have been discontinued.
See Ordering Information section for product status.

Table 2. MACH 5 Speed Grades

Device	Speed Grade ¹						
	-5	-6	-7	-10	-12	-15	-20
M5-128 ²			C	C, I	C, I	C, I	I
M5-128/1	C		C, I	C, I	C, I	C, I	I
M5LV-128	C		C, I	C, I	C, I	I	
M5-192/1	C		C, I	C, I	C, I	C, I	I
M5-256 ²			C	C, I	C, I	C, I	I
M5-256/1	C		C, I	C, I	C, I	C, I	I
M5LV-256	C		C, I	C, I	C, I	I	
M5-320		C	C, I	C, I	C, I	C, I	I
M5LV-320		C	C, I	C, I	C, I	C, I	I
M5-384		C	C, I	C, I	C, I	C, I	I
M5LV-384		C	C, I	C, I	C, I	C, I	I
M5-512		C	C, I	C, I	C, I	C, I	I
M5LV-512		C	C, I	C, I	C, I	C, I	I

Note:

1. C = Commercial grade, I = Industrial grade
2. /1 version recommended for new designs

With Lattice's unique hierarchical architecture, the MACH 5 family provides densities up to 512 macrocells to support full system logic integration. Extensive routing resources ensure pinout retention as well as high utilization. It is ideal for PAL[®] block device integration and a wide range of other applications including high-speed computing, low-power applications, communications, and embedded control. At each macrocell density point, Lattice offers several I/O and package options to meet a wide range of design needs (Table 3).

Table 3. MACH 5 Package and I/O Options ¹

	M5-128/1 M5LV-128		M5-192/1	M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
	5	3.3		5	3.3	5	3.3	5	3.3	5	3.3
100-pin TQFP	68	68, 74	68	68	68*, 74						
100-pin PQFP	68	68*	68*	68*	68						
144-pin TQFP		104			104						
144-pin PQFP	104	104*	104*	104*	104*						
160-pin PQFP	120	120	120	120	120	120*	120	120*	120	120*	120
208-pin PQFP				160	160	160	160	160	160	160	160
240-pin PQFP						184*	184*	184*	184*	184*	184*
256-ball BGA						192	192*	192*	192*	192*	192*
352-ball BGA										256	256

Note:

1. The I/O options indicated with a "*" are obsolete, please contact factory for more information.

Advanced power management options allow designers to incrementally reduce power while maintaining the level of performance needed for today's complex designs. I/O safety features allow for mixed-voltage design,

Select devices have been discontinued.
See Ordering Information section for product status.

and both the 3.3-V and the 5-V device versions are in-system programmable through an IEEE 1149.1 Test Access Port (TAP) interface.

FUNCTIONAL DESCRIPTION

The MACH 5 architecture consists of PAL blocks connected by two levels of interconnect. The **block interconnect** provides routing among 4 PAL blocks. This grouping of PAL blocks joined by the block interconnect is called a **segment**. The second level of interconnect, the **segment interconnect**, ties all of the segments together. The only logic difference between any two MACH 5 devices is the number of segments. Therefore, once a designer is familiar with one device, consistent performance can be expected across the entire family. All devices have four clock pins available which can also be used as logic inputs.

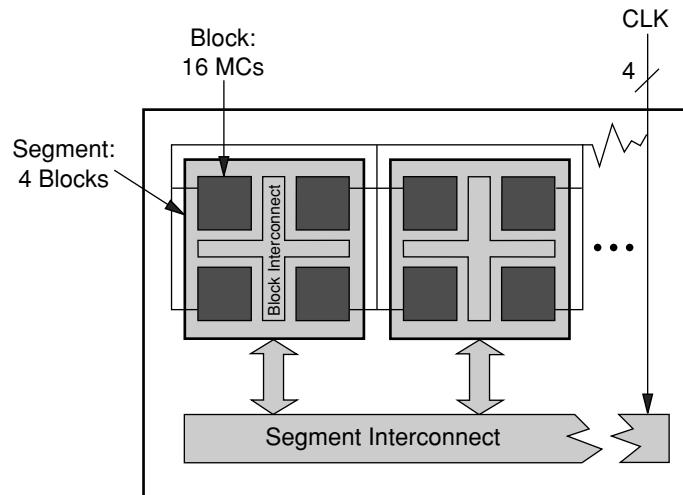


Figure 1. MACH 5 Block Diagram

20446G-001

The MACH 5 PAL blocks consist of the elements listed below (Figure 2). While each PAL block resembles an independent PAL device, it has superior control and logic generation capabilities.

- ◆ I/O cells
- ◆ Product-term array and Logic Allocator
- ◆ Macrocells
- ◆ Register control generator
- ◆ Output enable generator

I/O Cells

The I/Os associated with each PAL block have a path directly back to that PAL block called **local feedback**. If the I/O is used in another PAL block, the **interconnect feeder** assigns a **block interconnect** line to that signal. The interconnect feeder acts as an input switch matrix. The block and segment interconnects provide connections between any two signals in a device. The **block feeder** assigns block interconnect lines and local feedback lines to the PAL block inputs.

Select devices have been discontinued.
See Ordering Information section for product status.

MACH 5 TIMING MODEL

The primary focus of the MACH 5 timing model is to accurately represent the timing in a MACH 5 device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between **internal feedback** and **external feedback**. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF} is defined as the time it takes to go through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an "i". By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDi} + t_{BUF}$. A diagram representing the modularized MACH 5 timing model is shown in Figure 7. Refer to the Technical Note entitled *MACH 5 Timing and High Speed Design* for a more detailed discussion about the timing parameters.

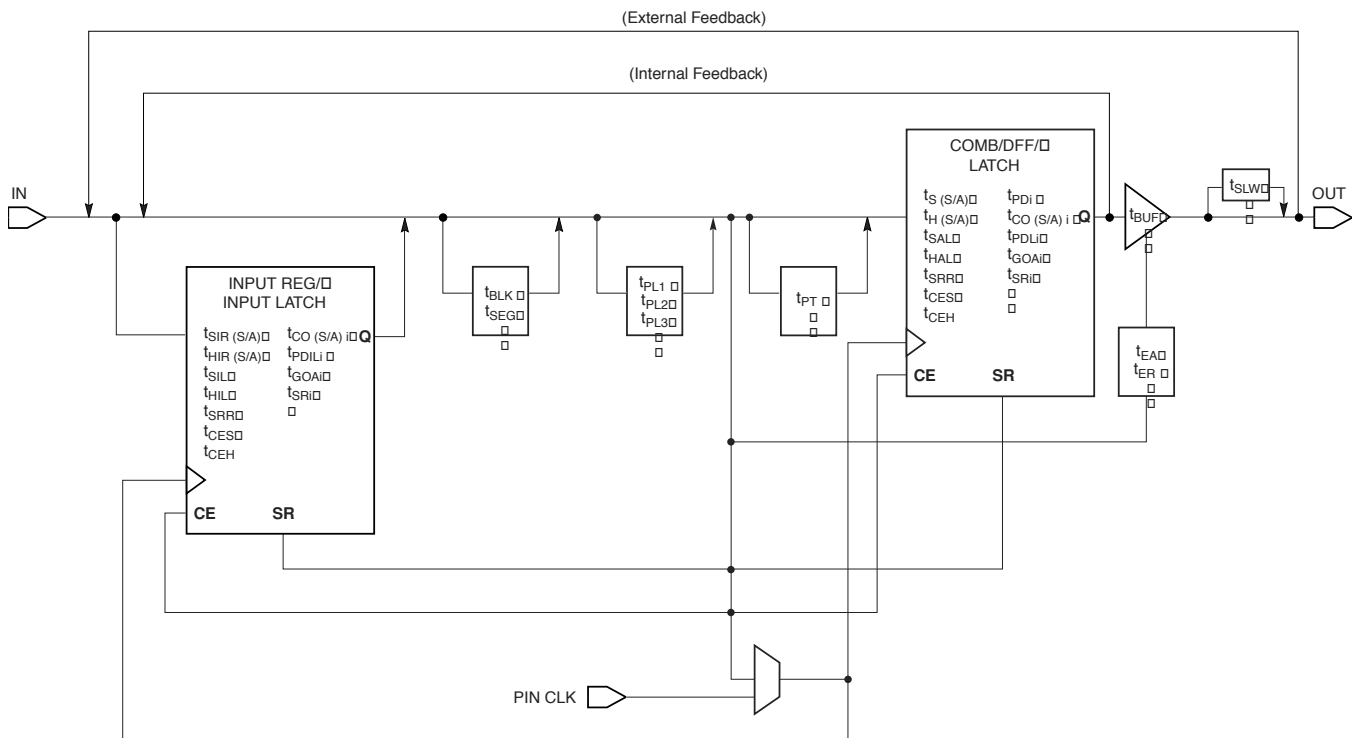
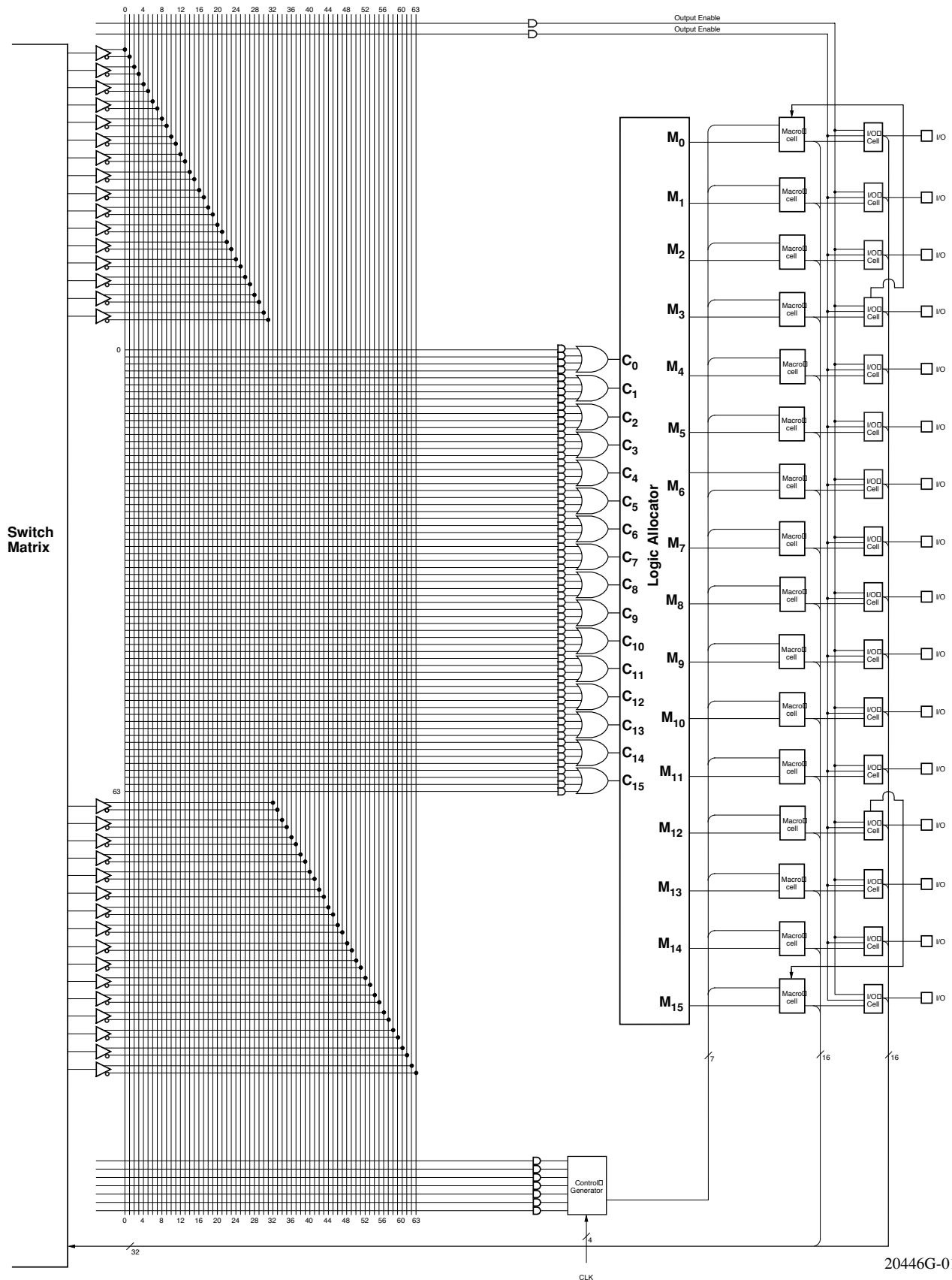


Figure 7. MACH 5 Timing Model

20446G-014

Select devices have been discontinued.
See Ordering Information section for product status.

MACH 5 PAL BLOCK

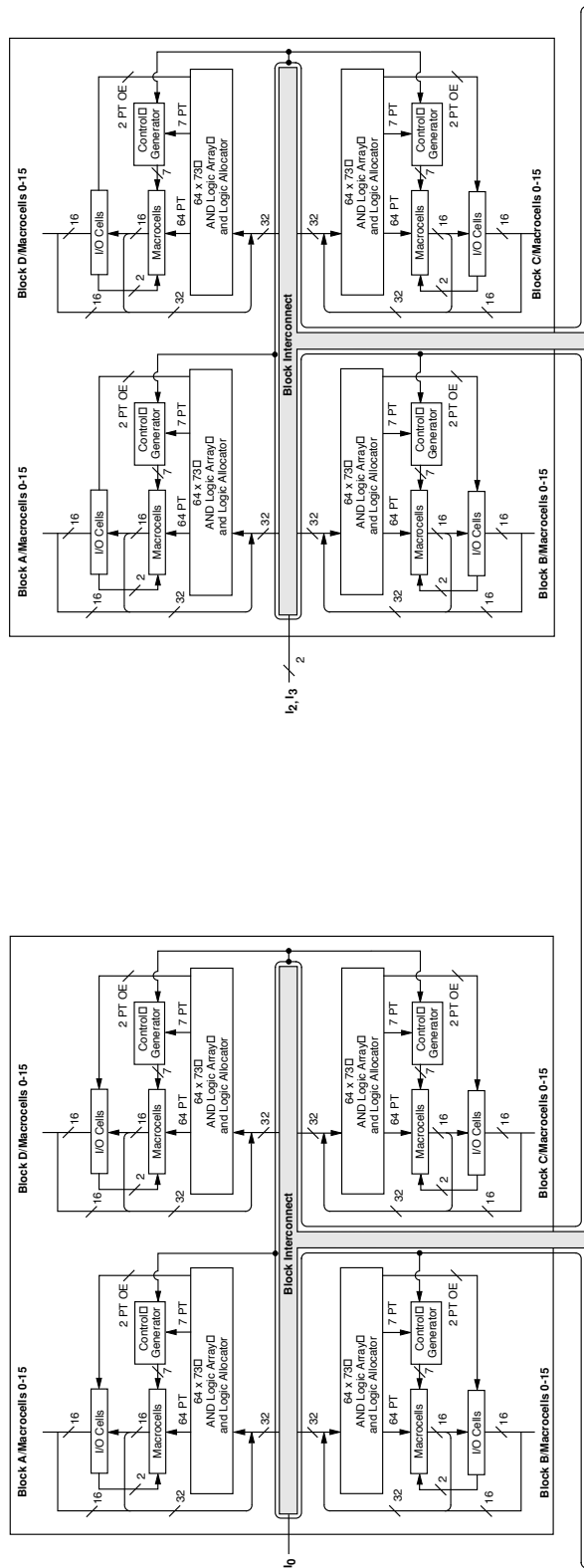


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See Ordering Information section for product status.

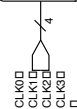
20446G-015

BLOCK DIAGRAM — M5-192/XXX

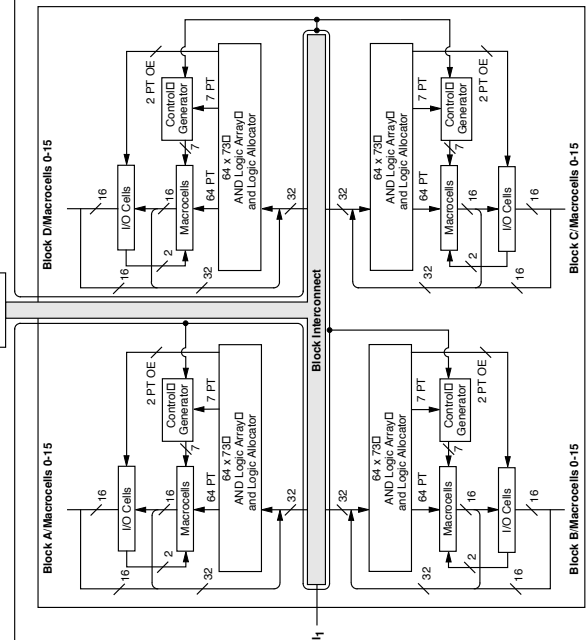
SEGMENT 2



SEGMENT INTERCONNECT



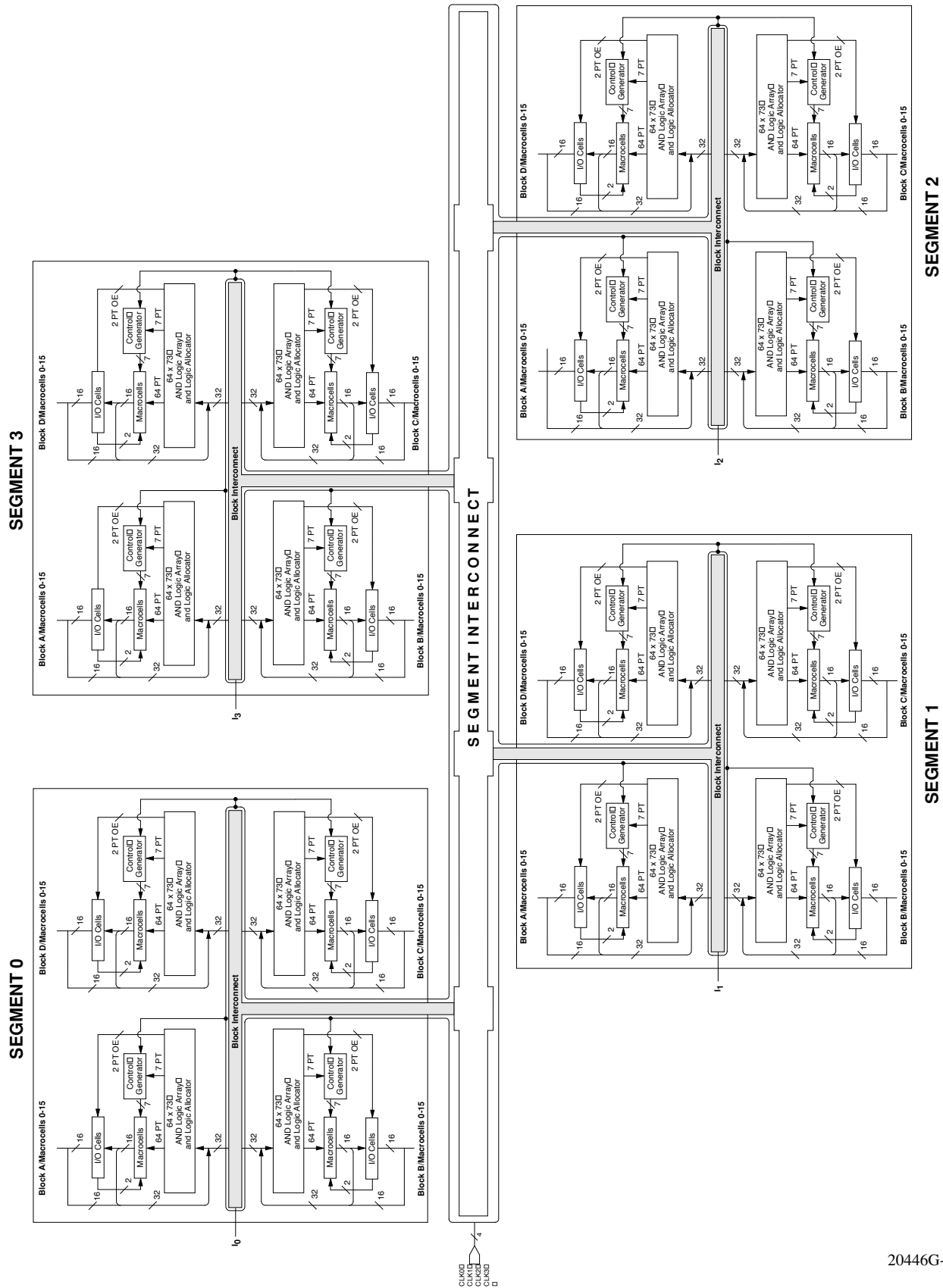
SEGMENT 1



Select devices have been discontinued.
See Ordering Information section for product status.

20446G-008

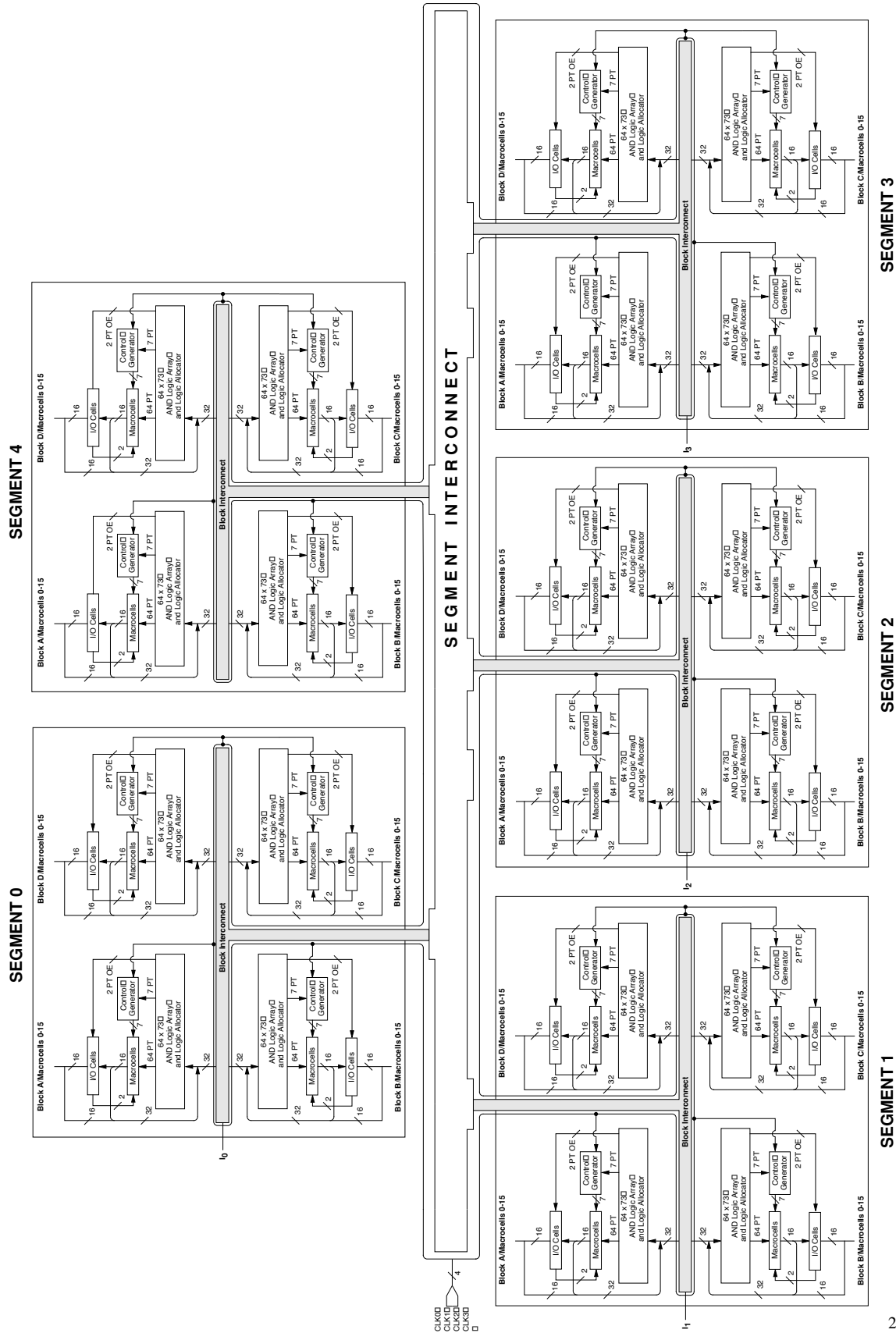
BLOCK DIAGRAM — M5(LV)-256/XXX



Select devices have been discontinued.
See Ordering Information section for product status.

20446G-009

BLOCK DIAGRAM — M5(LV)-320/XXX



Select devices have been discontinued.
See Ordering Information section for product status.

20446G-010

ABSOLUTE MAXIMUM RATINGS

M5LV

Storage Temperature. -65°C to +150°C
Device Junction Temperature. +130°C
Supply Voltage
with Respect to Ground -0.5 V to +4.5 V
DC Input Voltage -0.5 V to 5.5 V
Static Discharge Voltage 2000 V
Latchup Current (-40°C to +85°C) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air. 0°C to +70°C
Supply Voltage (V_{CC})
with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air. -40°C to +85°C
Supply Voltage (V_{CC})
with Respect to Ground. +3.0 V to +3.6 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description		Min	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$	$I_{OH} = -100 \mu A$	$V_{CC} - 0.2$		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = 3.2 \text{ mA}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 100 \mu A$		0.2	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 16 \text{ mA (Note 1)}$		0.5	V
V_{IH}	Input HIGH Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max (Note 2)}$		2.0	5.5	V
V_{IL}	Input LOW Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max (Note 2)}$		-0.3	0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6, V_{CC} = \text{Max (Note 3)}$			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max (Note 3)}$			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 4)}$		-15	-160	mA

Notes:

1. Total I_{OL} between ground pins should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
4. Not more than one output should be shorted at one time. Duration of the short-circuit should not exceed one second.

Select devices have been discontinued.
See Ordering Information section for product status.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

		-5		-6		-7		-10		-12		-15		-20		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Power Delays:																
t _{PL1}	Power level 1 delay (Note 2)		4.0 (5.0)		4.0		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)	ns
t _{PL2}	Power level 2 delay (Note 2)		6.0 (9.0)		6.0		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)	ns
t _{PL3}	Power level 3 delay (Note 2)		9.0 (17.5)		9.0		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)	ns
Additional Cluster Delay:																
t _{PT}	Product term cluster delay		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
Interconnect Delays:																
t _{BLK}	Block interconnect delay		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns
t _{SEG}	Segment interconnect delay		4.5		4.5		5.0		6.0		6.0		6.0		6.0	ns
Reset and Preset Delays:																
t _{SRI}	Asynchronous reset or preset to internal register output		6.0		8.0		8.0		10.0		12.0		14.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		8.0		10.0		10.0		12.0		14.0		16.0		18.0	ns
t _{SRR}	Reset and set register recovery time	5.5		7.5		7.5		8.0		9.0		10.0		11.0		ns
t _{SRW}	Asynchronous reset or preset width	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
Clock Enable Delays:																
t _{CES}	Clock enable setup time	4.0		5.0		5.0		6.0		7.0		7.0		8.0		ns
t _{CEH}	Clock enable hold time	3.0		4.0		4.0		5.0		6.0		6.0		7.0		ns
Width:																
t _{WLS}	Global clock width low (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WHS}	Global clock width high (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WHA}	Product term clock width high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{GWA}	Gate width low (for low transparent) or high (for high transparent)	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WIR}	Input register clock width low or high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns

Select devices have been discontinued.
See Ordering Information section for product status.

CAPACITANCE¹

Parameter Symbol	Parameter Description	Test conditions		Typ	Unit
C_{IN}	I/CLK pin	$V_{IN} = 2.0\text{ V}$	3.3 V or 5 V, 25° C, 1 MHz	12	pF
$C_{I/O}$	I/O pin	$V_{OUT} = 2.0\text{ V}$	3.3 V or 5 V, 25° C, 1 MHz	10	pF

1. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where these parameters may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power. For a more detailed discussion about MACH 5 power consumption, refer to the application note entitled *MACH 5 Power* in the Application Notes section on the Lattice Data Book CD-ROM or Lattice web site.

I_{CC} CURVES AT HIGH /LOW POWER MODES

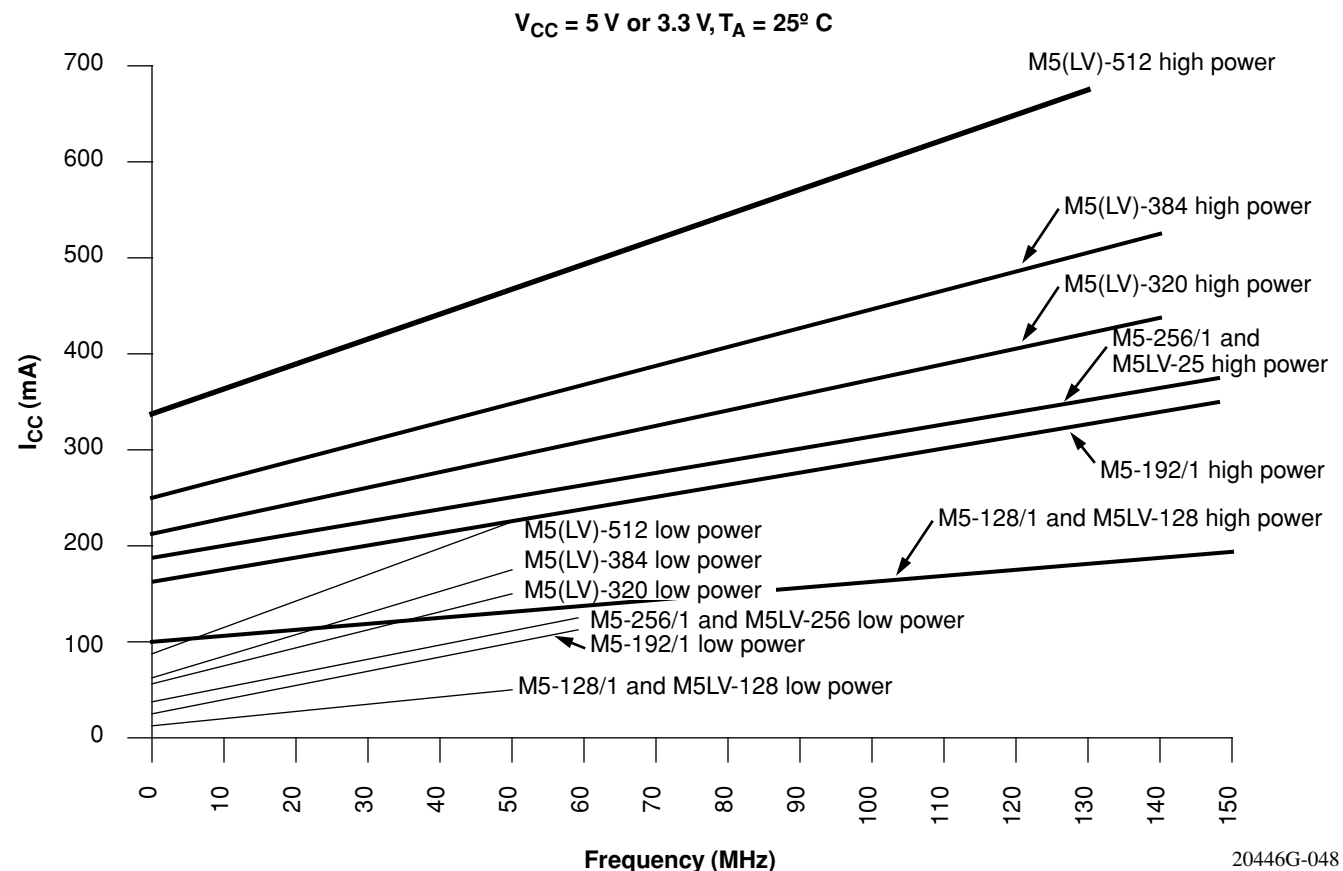


Figure 8. I_{CC} Curves at High/Low Power Modes

Select devices have been discontinued. See Ordering Information section for product status.

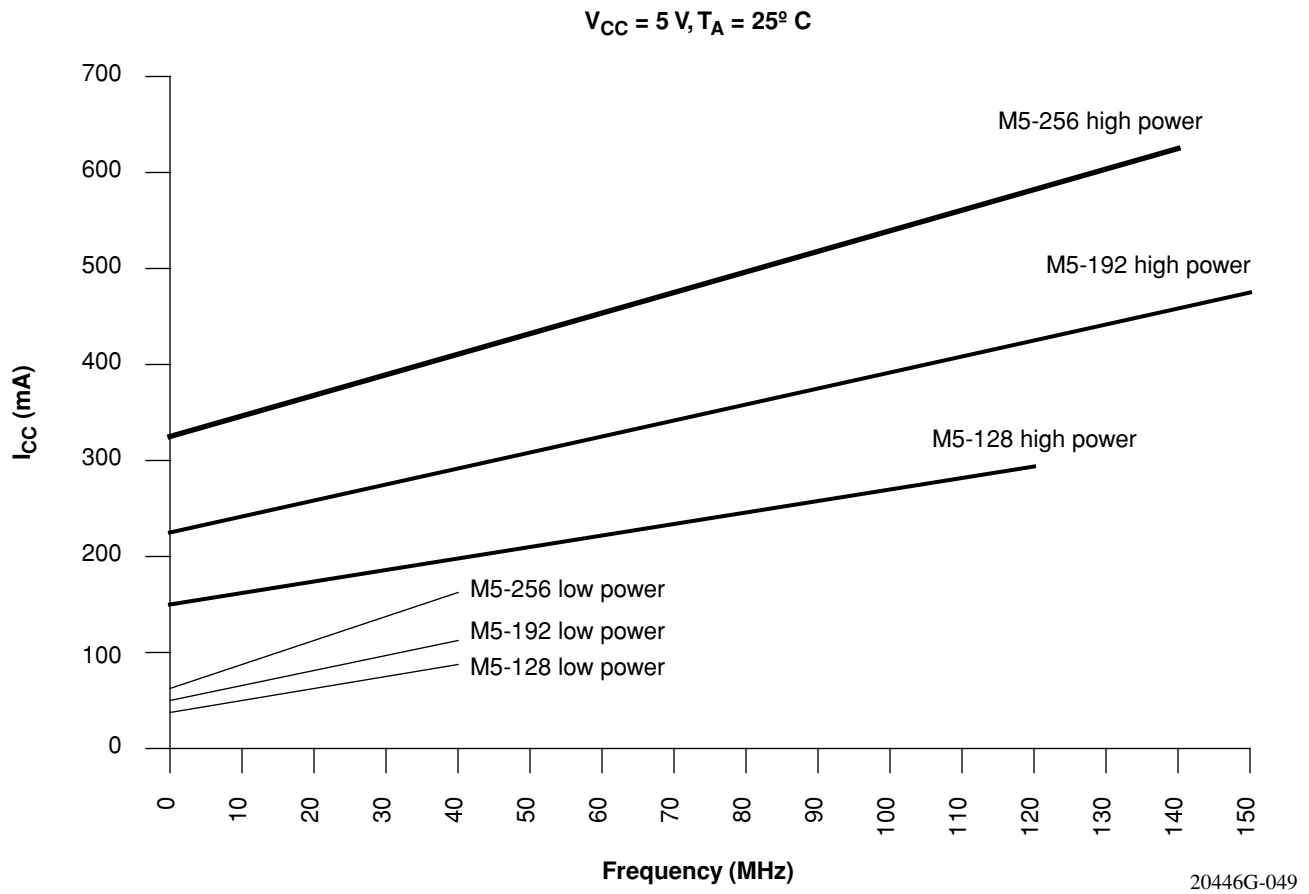


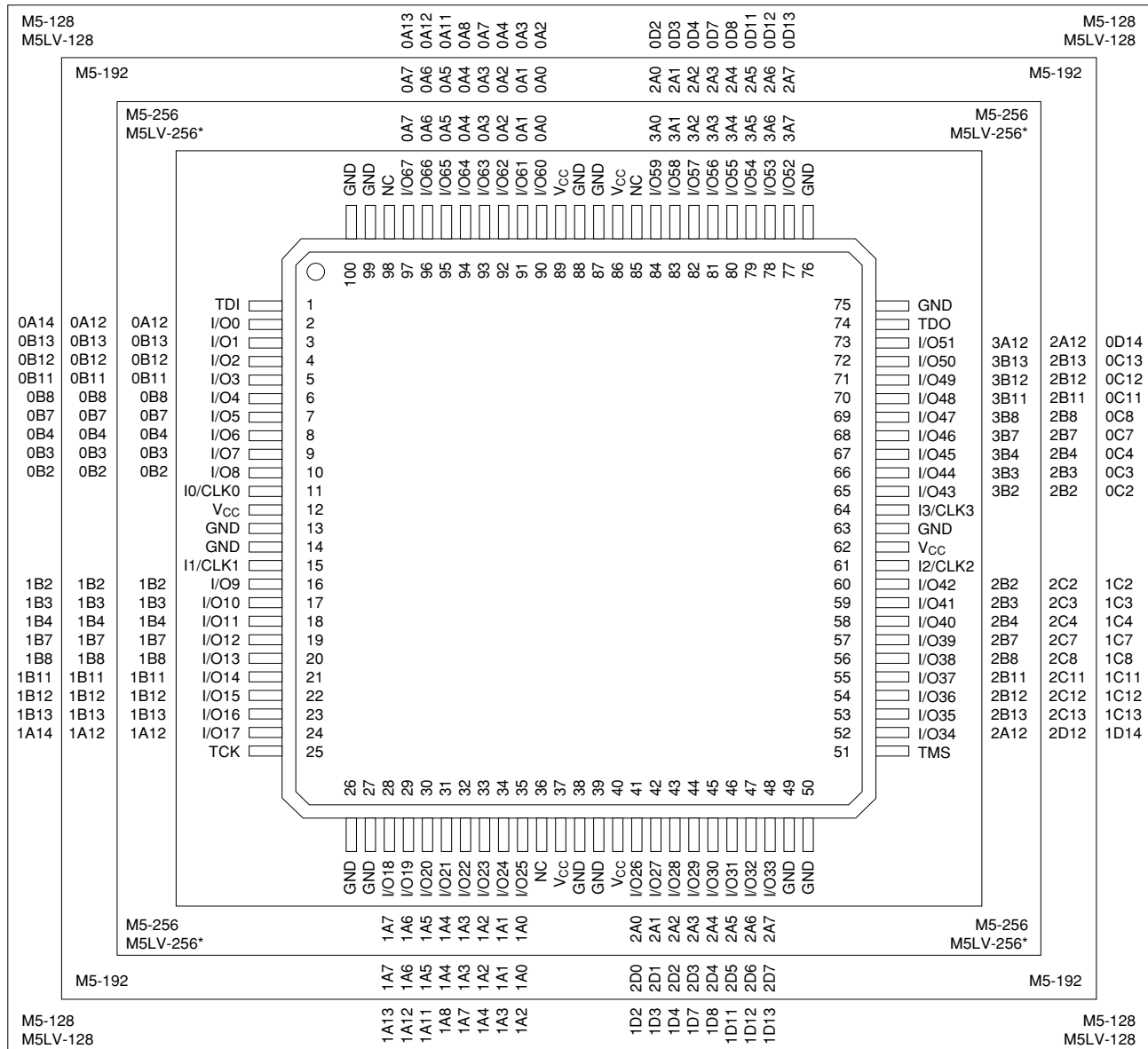
Figure 9. I_{CC} Curves at High/Low Power Modes

Select devices have been discontinued.
See Ordering Information section for product status.

100-PIN TQFP CONNECTION DIAGRAM – 68 I/O

Top View

100-Pin TQFP (68 I/O)



*Package obsolete, contact factory.

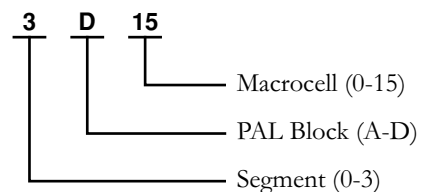
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-017

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

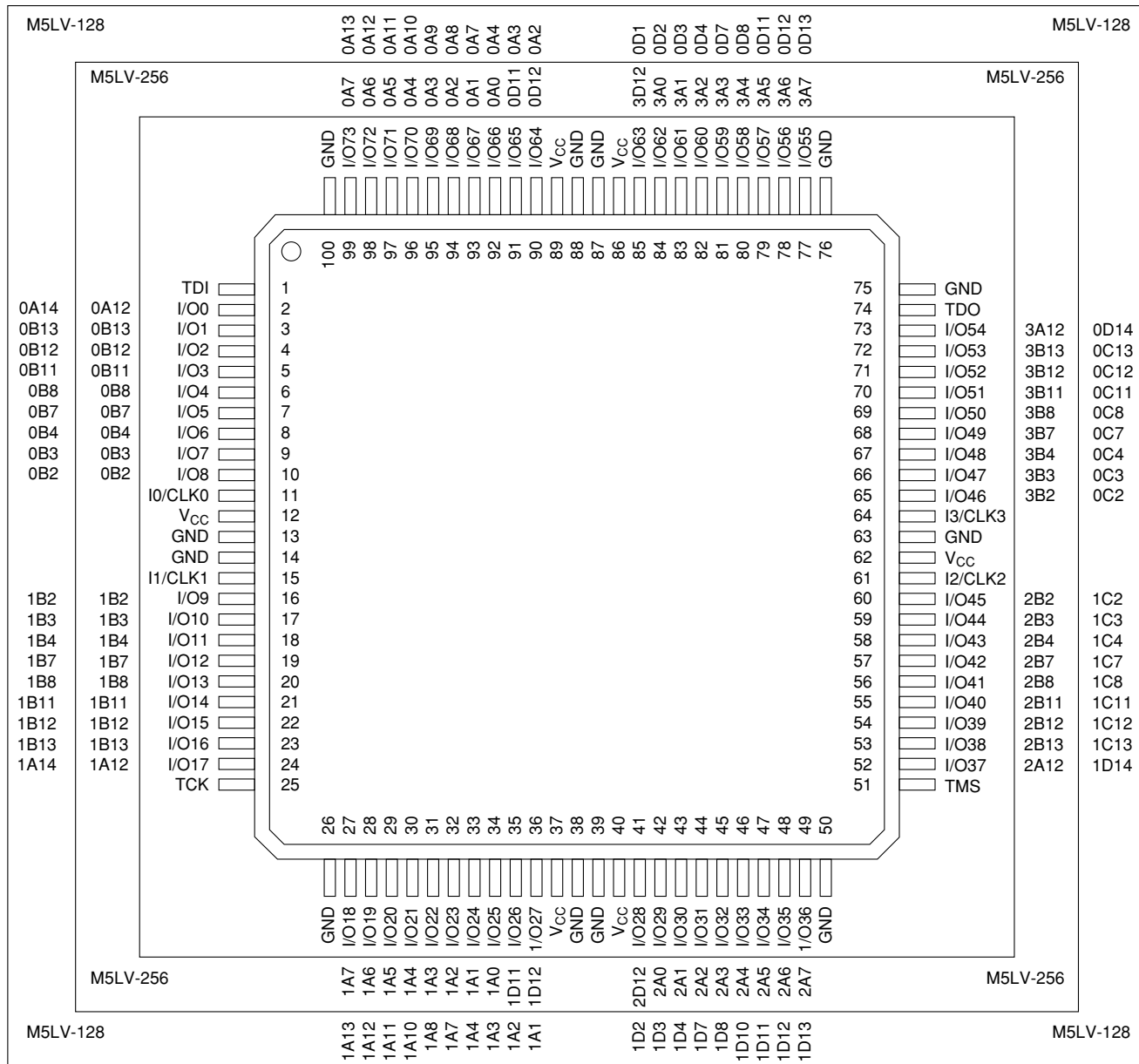
V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



100-PIN TQFP CONNECTION DIAGRAM – 74 I/O

Top View

100-Pin TQFP (74 I/O)



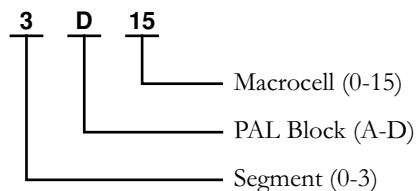
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-018

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

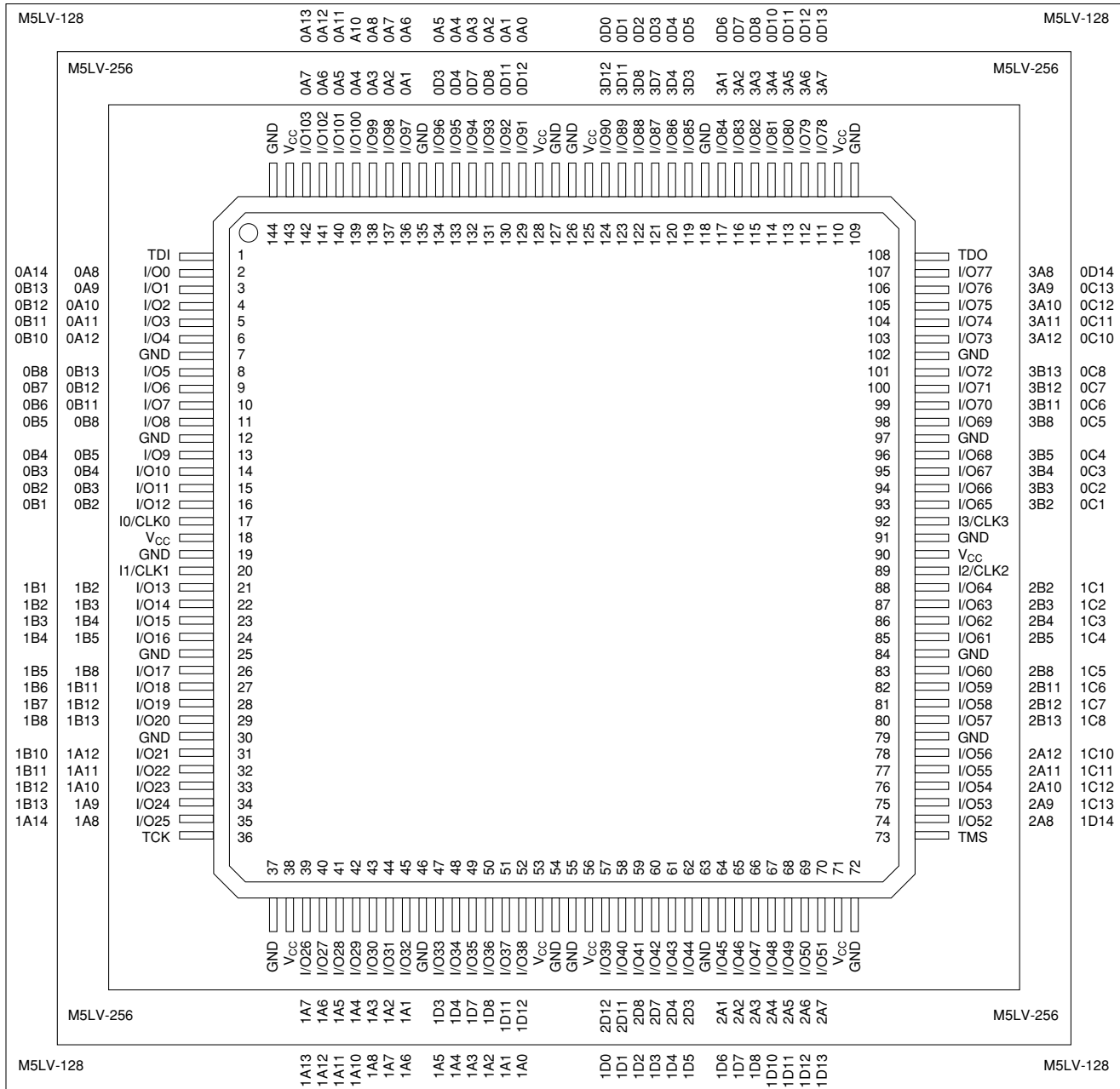
V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



144-PIN TQFP CONNECTION DIAGRAM

Top View

144-Pin TQFP



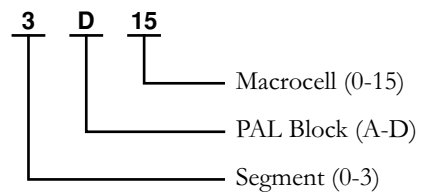
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-020

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

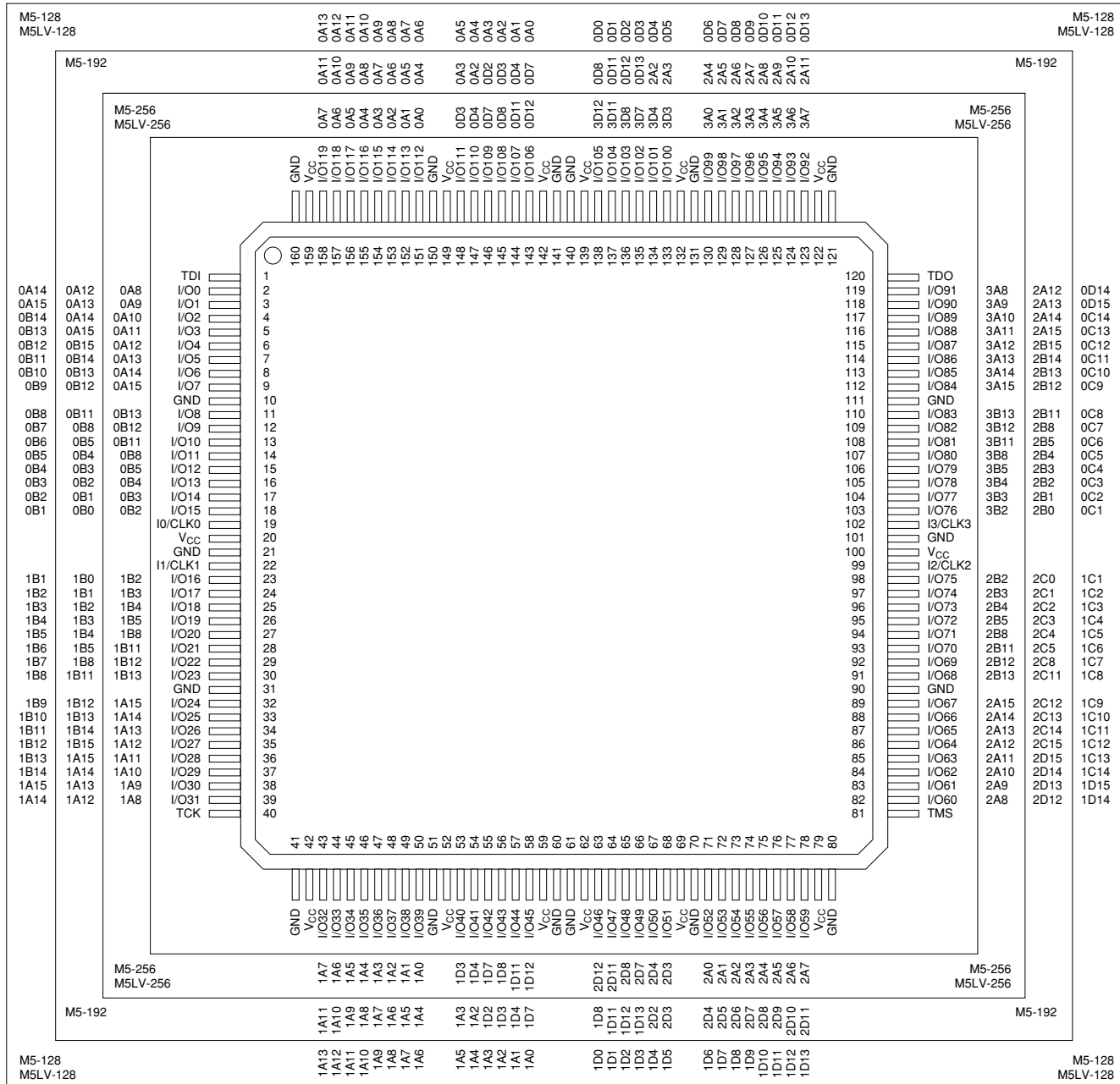
V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



160-PIN PQFP CONNECTION DIAGRAM

Top View

160-Pin PQFP (128, 192, 256 Macrocells)



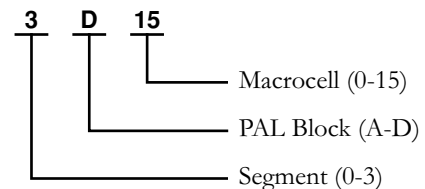
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-021

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



208-PIN PQFP (WITH INTERNAL HEAT SPREADER) CONNECTION DIAGRAM Top View

208-Pin PQFP (320, 384, 512 Macrocells)



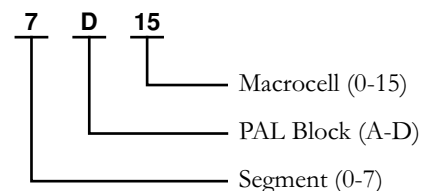
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-024

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (I/O Pin-outs)

256-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	
1	GND	GND	I/O181	I/O182	I/O183	GND	I/O184	GND	I/O185	I/O186	GND	I/O187	GND	I/O188	GND	I/O189	I/O190	I/O191	GND	GND	
2	GND	I/O164	I/O165	I/O166	I/O167	I/O168	I/O169	I/O170	I/O171	I/O172	I/O173	I/O174	I/O175	I/O176	I/O177	I/O178	I/O179	I/O180	GND	GND	
3	GND	I/O148	V _{CC}	I/O149	I/O150	I/O151	I/O152	I/O153	I/O154	I/O155	I/O156	I/O157	I/O158	I/O159	I/O160	I/O161	I/O162	V _{CC}	I/O163	GND	
4	I/O134	I/O135	I/O136	V _{CC}	TDO	I/O137	V _{CC}	I/O138	I/O139	I/O140	I/O141	I/O142	I/O143	V _{CC}	I/O144	TMS	V _{CC}	I/O145	I/O146	I/O147	
5	I/O128	I/O129	I/O130	V _{CC}	Pin Designations CLK = Clock GND = Ground I = Input I/O = Input/Output NC = No Connect V_{CC} = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out	GND	I/O116	I/O108	GND	GND	GND	GND	I/O76	I/O70	GND	I/O58	I/O44	GND	I/O45	V _{CC}	I/O46
6	I/O122	I/O123	I/O124	V _{CC}		I/O110	I/O103	I/O97	I/O98	I/O96	I/O90	I/O84	I/O77	I/O71	I/O64	I/O59	I/O46	I/O41	I/O35	I/O29	I/O13
7	V _{CC}	I/O118	I/O121	V _{CC}		I/O111	I/O104	I/O98	I/O92	I/O86	I/O85	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
8	I/O112	I/O109	I/O118	V _{CC}		I/O111	I/O104	I/O98	I/O92	I/O86	I/O85	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
9	GND	I/O102	I/O103	I/O104		I/O104	I/O98	I/O92	I/O86	I/O85	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
10	GND	I/O96	I/O97	I/O98		I/O98	I/O92	I/O86	I/O85	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
11	GND	I/O90	I/O91	I/O92		I/O92	I/O86	I/O85	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
12	GND	I/O84	I/O85	I/O86		I/O86	I/O85	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
13	I/O76	I/O77	I/O78	I/O79		I/O79	I/O78	I/O72	V _{CC}	I/O66	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
14	I/O70	I/O71	I/O72	V _{CC}		V _{CC}	I/O66	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	I/O55	I/O49	I/O43	I/O14
15	GND	I/O64	I/O65	I/O66		I/O66	I/O65	I/O60	I/O58	I/O54	I/O48	I/O42	I/O36	I/O30	I/O24	I/O18	I/O12	I/O06	I/O00	I/O00	I/O00
16	I/O58	I/O59	I/O60	V _{CC}		V _{CC}	I/O67	I/O61	I/O62	I/O63	I/O64	I/O65	I/O66	I/O67	I/O68	I/O69	I/O70	I/O71	I/O72	I/O73	I/O74
17	I/O44	I/O45	I/O46	V _{CC}		TDI	I/O43	I/O37	I/O31	I/O25	I/O19	I/O13	I/O07	I/O01	I/O01	I/O01	I/O01	I/O01	I/O01	I/O01	I/O01
18	GND	I/O28	V _{CC}	I/O29		I/O30	I/O36	I/O30	I/O24	I/O18	I/O12	I/O06	I/O00	I/O00	I/O00	I/O00	I/O00	I/O00	I/O00	I/O00	I/O00
19	I/O11	I/O12	I/O13	I/O14		I/O15	I/O16	I/O17	I/O18	I/O19	I/O20	I/O21	I/O22	I/O23	I/O24	I/O25	I/O26	I/O27	I/O28	I/O29	I/O30
20	GND	GND	I/O0	I/O1		I/O2	GND	I/O3	GND	I/O4	GND	I/O5	I/O6	GND	I/O7	GND	I/O8	I/O9	I/O10	GND	GND

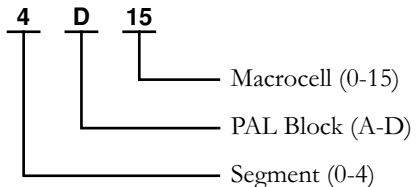
20446G-026

Select devices have been discontinued.
See Ordering Information section for product status.

256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (Macrocell Association)

256-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y		
1	GND	GND	3A11	3D15	3D12	GND	3D7	GND	3D3	3D2	GND	2D2	GND	2D7	GND	2D10	2D13	2D15	GND	GND	1	
2	GND	3B2	3A3	3A8	3A13	3D13	3D9	3D8	3D4	I3/CLK3	I2/CLK2	2D3	2D4	2D8	2D12	2A15	2A13	2A12	2A9	2A7	2	
3	GND	3B8	V _{CC}	3A2	3A4	3A12	3D14	3D10	3D5	3D0	2D0	2D5	2D9	2D14	2A14	2A10	2A8	V _{CC}	2A3	GND	3	
4	3B13	3B11	3B3	V _{CC}	TDO	3A7	V _{CC}	3D11	3D6	3D1	2D1	2D6	2D11	V _{CC}	2A11	TMS	V _{CC}	2A6	2A2	2A0	4	
5	4B14	4B15	3B4	V _{CC}	Pin Designations CLK = Clock GND = Ground I = Input I/O = Input/Output NC = No Connect V_{CC} = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out 												V _{CC}	2A4	2A1	2B0	2B1	5
6	GND	4B11	3B12	3B7													V _{CC}	2A1	2B4	GND	6	
7	4B8	4B10	4B13	V _{CC}													V _{CC}	2B2	2B5	2B7	7	
8	4B4	4B6	4B9	4B12													2B3	2B6	2B9	2B11	8	
9	GND	4B3	4B5	4B7													2B8	2B10	2B12	GND	9	
10	GND	4B0	4B1	4B2													2B13	2B14	2B15	GND	10	
11	GND	4A0	4A1	4A2													1B13	1B14	1B15	GND	11	
12	GND	4A3	4A5	4A7													1B8	1B10	1B12	GND	12	
13	4A4	4A6	4A9	4A12													1B3	1B6	1B9	1B11	13	
14	4A8	4A10	4A13	V _{CC}													V _{CC}	1B2	1B5	1B7	14	
15	GND	4A11	0B12	0B7													1A4	1A1	1B4	GND	15	
16	4A14	4A15	0B4	V _{CC}													V _{CC}	1A5	1B0	1B1	16	
17	0B13	0B11	0B3	V _{CC}	TDI	0A7	V _{CC}	0D11	0D6	0D1	1D1	1D6	1D11	V _{CC}	1A11	TCK	V _{CC}	1A6	1A2	1A0	17	
18	GND	0B8	V _{CC}	0A2	0A4	0A12	0D14	0D9	0D5	0D0	1D0	1D5	1D10	1D14	1A14	1A10	1A8	V _{CC}	1A3	GND	18	
19	0B2	0A3	0A8	0A11	0A13	0D12	0D8	0D4	0D3	I0/CLK0	I1/CLK1	1D4	1D8	1D9	1D13	1A15	1A12	1A9	1A7	GND	19	
20	GND	GND	0D15	0D13	0D10	GND	0D7	GND	0D2	GND	1D2	1D3	GND	1D7	GND	1D12	1D15	1A13	GND	GND	20	

Select devices have been discontinued.
See Ordering Information section for product status.

20446G-029

